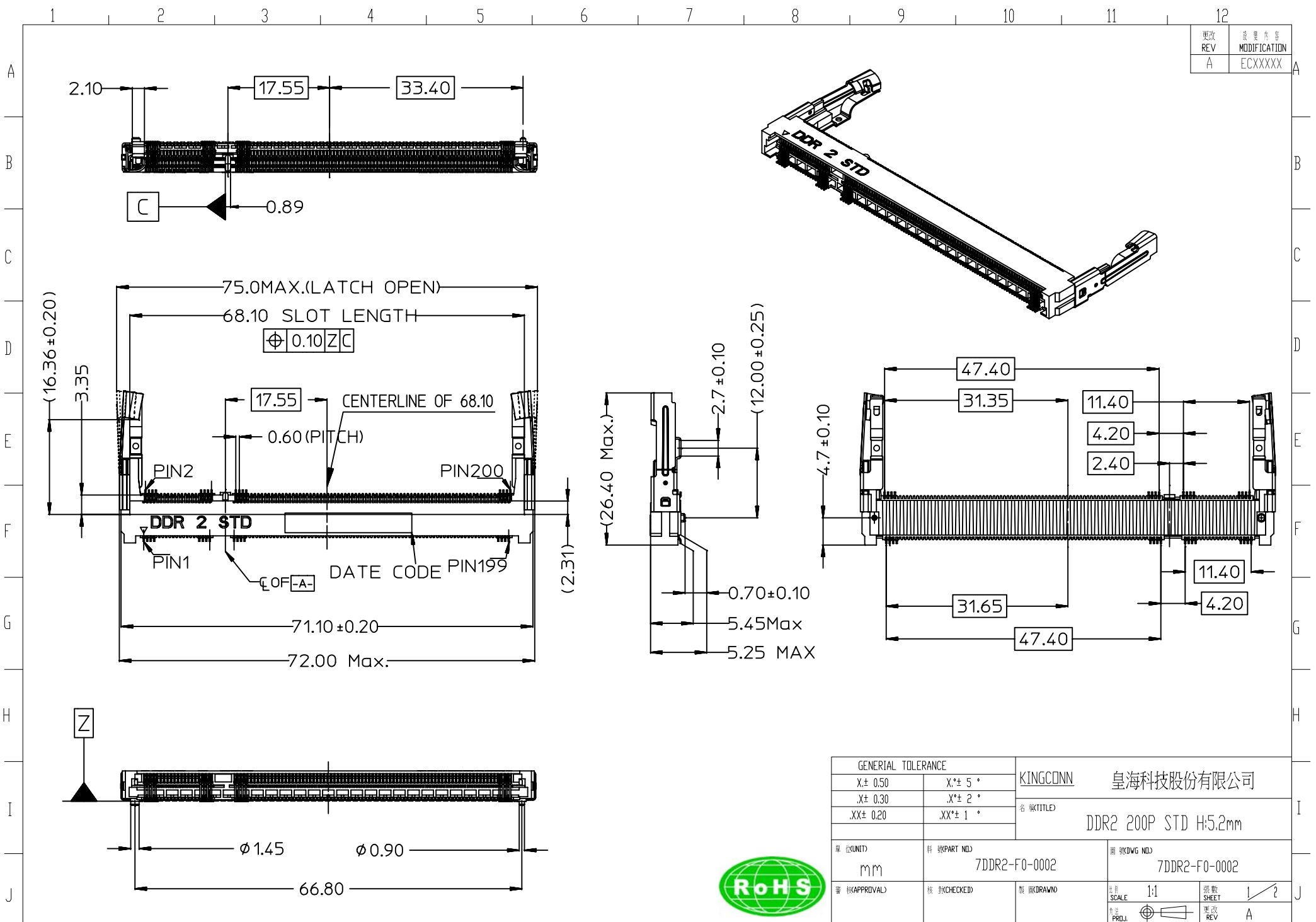
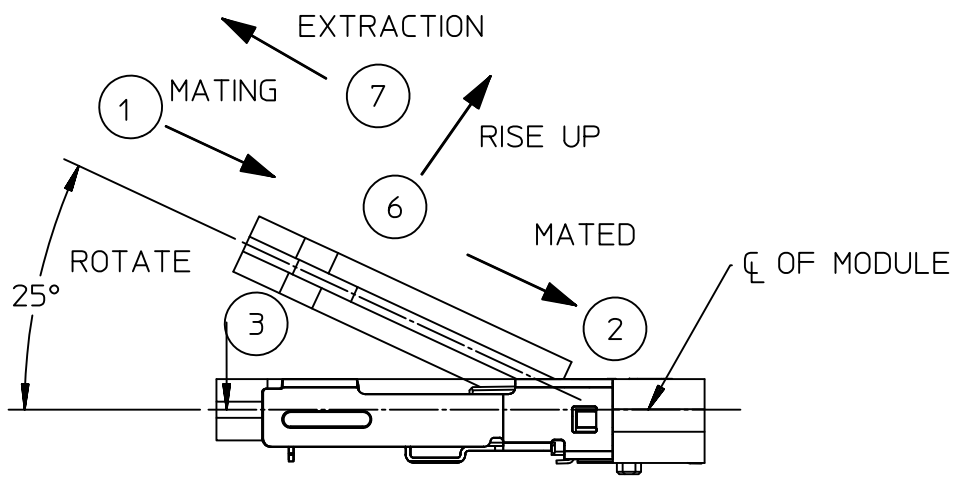


更改 REV	修改内容 MODIFICATION
A	ECXXXXX



GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X $\pm$ 0.50	X° $\pm$ 5°	名 稱(TITLE) DDR2 200P STD H:5.2mm	
.X $\pm$ 0.30	.X° $\pm$ 2°		
.XX $\pm$ 0.20	.XX° $\pm$ 1°		
單 位(UNIT) mm	料 號(PART NO.) 7DDR2-F0-0002	圖 號(DWG NO.) 7DDR2-F0-0002	
審核(APPROVAL)	檢 核(CHECKED)	製 圖(DRAWN)	SCALE 1:1 圖 號(SHEET) 1/2 製 改 REV A

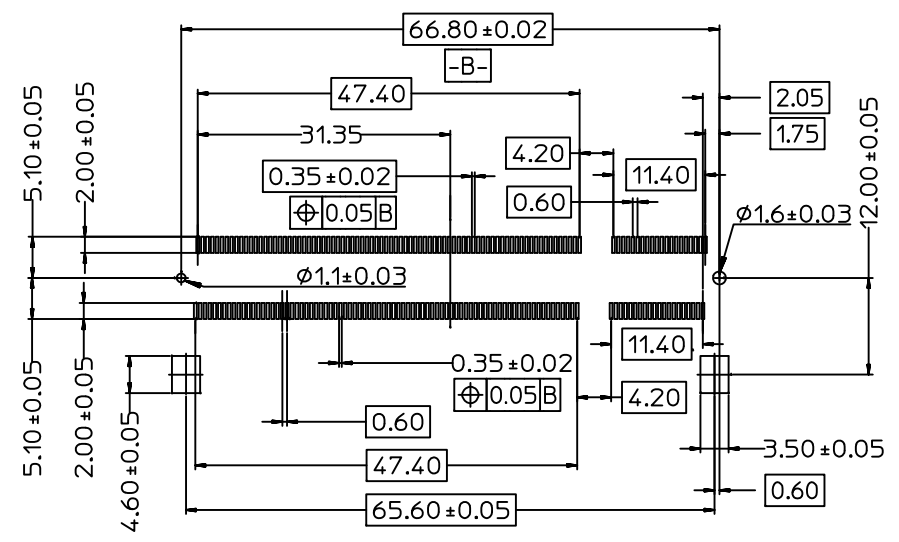
更改 REV	变更记录 MODIFICATION
A	ECXXXXX



- MATE: (5) (4) LOCK
- UNLOCK: (1) (4) MATE AND UNMATE GUIDE
- UNMATE: (5) (7)

NOTE:

- MATERIAL:  
HOUSING: LCP, UL94V-0, COLOR: BLACK  
CONTACTS: COPPER ALLOY,  
LATCH: STAINLESS STEEL
- FINISH:  
CONTACT AREA: GOLD PLATED OVER 0.762 MICRON/30u" MIN.NICKEL.  
SOLDER TAIL AREA: GOLD FLASH OVER 0.762 MICRON/30u" MIN.NICKEL.  
LATCH: 1.27 MICRON/50u"MIN. MATT TIN OVER 0.762 MICRON/30u" MIN. NICKEL.
- RECOMMENDED MODULE LAYOUT SHALL BE AS PER JEDEC SPECIFCATION
- PRODUCT SPECIFICATION:N/A
- PART SHALL BE PACKED: N/A
- EDGE OF CONTACT PADS SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS.



RECOMMEND PCB LAYOUT

GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司
X± 0.50	X*± 5 °	
.X± 0.30	.X*± 2 °	
.XX± 0.20	.XX*± 1 °	名 (TITLE) DDR2 200P STD H:5.2mm
单 (UNIT) mm	料 (PART NO.) 7DDR2-F0-0002	图 (DWG NO.) 7DDR2-F0-0002
审 (APPROVAL)	核 (CHECKED)	製 (DRAWN)
SCALE 1:1		张数 SHEET 2/2
PROJ.		更改 REV A

